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MT29GZ5A5BPGGA-53IT

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Specs

Orderable Parts for: MT29GZ5A5BPGGA-53IT

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	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT29GZ5A5BPGGA-53IT.87J	Sampling	N/A	JZ080	N/A	N/A	No		N/A

Detailed Specifications

Part Status Code	Sampling	**NAND Density**	4Gb	**DRAM Type**	LPDDR4	**DRAM Density**	4Gb
Bus Width	x8	**Secondary Bus Width**	x32	**RoHS**	Yes	**Voltage**	1.8V
Package	WFBGA	**Pin Count**	149-ball	**Clock Rate**	1866 MHz	**Operating Temp**	-40C to +85C

RoHS Certificates

RoHS Certificates

RoHS Certificate of Compliance (PDF)

Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2011/65/EU and 2015/863/EU, a.k.a. Restriction of Hazardous Substances (RoHS) Directive (Recast) without exemptions.

File Type: (PDF)   **Updated:** 09/2018

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China RoHS Certificate (PDF)

Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.

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Documentation & Support

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Technical Notes

SEARCH (2) NAND-BASED MCP TECHNICAL NOTES

Technical Notes

TN-00-01: Moisture Sensitivity of Plastic Packages (PDF)

(TN-00-01) This technical note describes shipping procedures for preventing memory devices from absorbing moisture and recommendations for baking devices exposed to excessive moisture.

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Technical Notes

TN-10-08: Thermal Implications for LPDDR Die Stacks (PDF)

(TN-10-08) This technical note presents a case study of a handset simulation in which an LPDRAM is stacked on an application processor (PoP) and the resulting thermal-profile modeling. This note also explains how thermal detection features included in LPDDR and LPDDR2 can be used to...

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Customer Service Notes

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Customer Service Note

Product Marks, Product Labels, and Packaging Labels (PDF)

(CSN-11) The first section of this customer service note describes the product marks and labels we place on our devices. The second section describes the labels used on and in our packaging.

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Micron Component and Module Packaging (PDF)

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(CSN-16) Explanation of Micron packaging labels and procedures.

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Hybrid Memory Cube	Financial Services	Supercomputing Memory	Authorized Distributors	History of Innovation
Multichip Packages	Industrial Memory Solutions		Legal	Locations
Memory Cards	Mobile Memory Solutions		Site Map	Our Commitment
Solid State Drives	Networking Innovations		Surplus Equipment	Investor Relations
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